

Electronic Patent Application Fee Transmittal

| Application Number: | 10723096 | | | |
|--|-----------------------------|-----------------|---------------|-----------------------------|
| Filing Date: | 26-Nov-2003 | | | |
| Title of Invention: | Molding compound | | | |
| First Named Inventor/Applicant Name: | John E. Kendall | | | |
| Filer: | Scott Chapple/Elise Nichols | | | |
| Attorney Docket Number: | 62806A (1062-023) | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 2 months with \$0 paid | 1252 | 1 | 450 | 450 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-----------------------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Request for continued examination | 1801 | 1 | 790 | 790 |
| Total in USD (\$) | | | | 1240 |